L Number	Hits	Search Text	DB	Time stamp
1	374938	(test wiring circuit) adj2 (board substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:43
8	257738	(spring coil) near6 (ball bump lead contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:45
15	22662	((test wiring circuit) adj2 (board substrate)) and ((spring coil) near6 (ball bump lead contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:46
22	3450	(((test wiring circuit) adj2 (board substrate)) and ((spring coil) near6 (ball bump lead contact))) and (324/$.ccls. 361/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:56
29	6240	324/754,765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:47
36	494	(((test wiring circuit) adj2 (board substrate)) and ((spring coil) near6 (ball bump lead contact))) and 324/754,765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:53
43	420130	(ball bump lead contact) near12 (opening aperture aperature via hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:56
50	29251	((spring coil) near6 (ball bump lead contact)) near12 (opening aperture aperature via hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:56
57	2990	((test wiring circuit) adj2 (board substrate)) and ((ball bump lead contact) near12 (opening aperture aperature via hole)) and (((spring coil) near6 (ball bump lead contact)) near12 (opening aperture aperature via hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 15:56
64	442	(((test wiring circuit) adj2 (board substrate)) and ((ball bump lead contact) near12 (opening aperture aperature via hole)) and (((spring coil) near6 (ball bump lead contact)) near12 (opening aperture aperature via hole))) and (324/$.ccls. 361/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 16:16
71	4376	324/765-769.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 16:17
78	11	(((test wiring circuit) adj2 (board substrate)) and ((ball bump lead contact) near12 (opening aperture aperature via hole)) and (((spring coil) near6 (ball bump lead contact)) near12 (opening aperture aperature via hole))) and 324/765-769.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 16:18

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85	176	((spring coil) near6 (ball bump lead contact)) and 324/765-769.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 16:54
92	1034	((spring coil) near6 (ball bump lead contact)) and (PGA BGA ((ball pin) adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 17:04

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